LTCC Multi Layer Ceramic Coupler- 1608 (0603) size

- **RFCPL1608070P0T Series**
- **AMPS/GSM/ DCS/PCS/ISM2.4 GHz Band Application**

FEATURES

- Miniature footprint: 1.6 X 0.8 X 0.7 mm^3
- Low ProfileThickness.
- Low Insertion loss and high isolation.
- LTCC process

APPLICATIONS

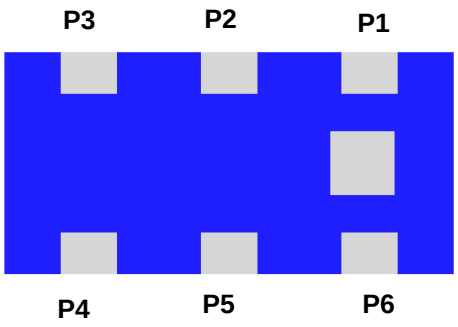
- For AMPS/GSM applications
- For DCS/PCS applications
- For Bluetooth, Wireless LAN 802.11b/g/ n, HomeRF

ELECTRICAL CHARACTERISTICS

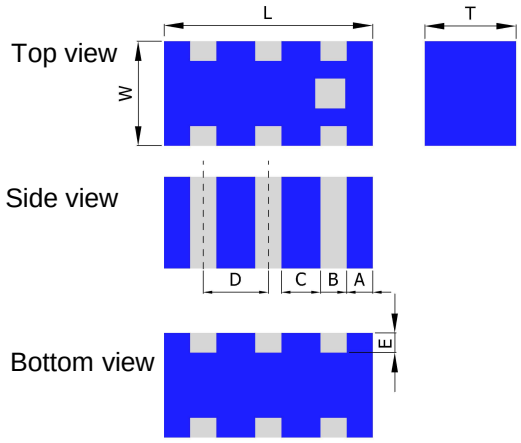
Item	Specification
Frequency Range	698 ~ 2690 MHz
VSWR	1.5 max
Impedance (Ω)	50
Insertion Loss (dB)	0.20 max. at 698~ 960 MHz 0.22 max. at 1427.9~ 2170 MHz 0.25 max. at 2300~ 2690 MHz
Coupling	23.0 ~ 27.0 dB@ 698~ 915 MHz 21.5 ~ 26.5 dB@ 1427.9 ~ 2025 MHz 22.5 ~ 27.5 dB@ 2300~ 2620 MHz
Directivity	20.0 min. dB @ 698 ~ 2690 Mhz

Taping Quantity …….: 4000pcs per 7” reel
Operating Temperature Range : -40~ +85℃
Storage Temperature Range : -10~ +40℃
Humidity : 30 to 70% relative humidity

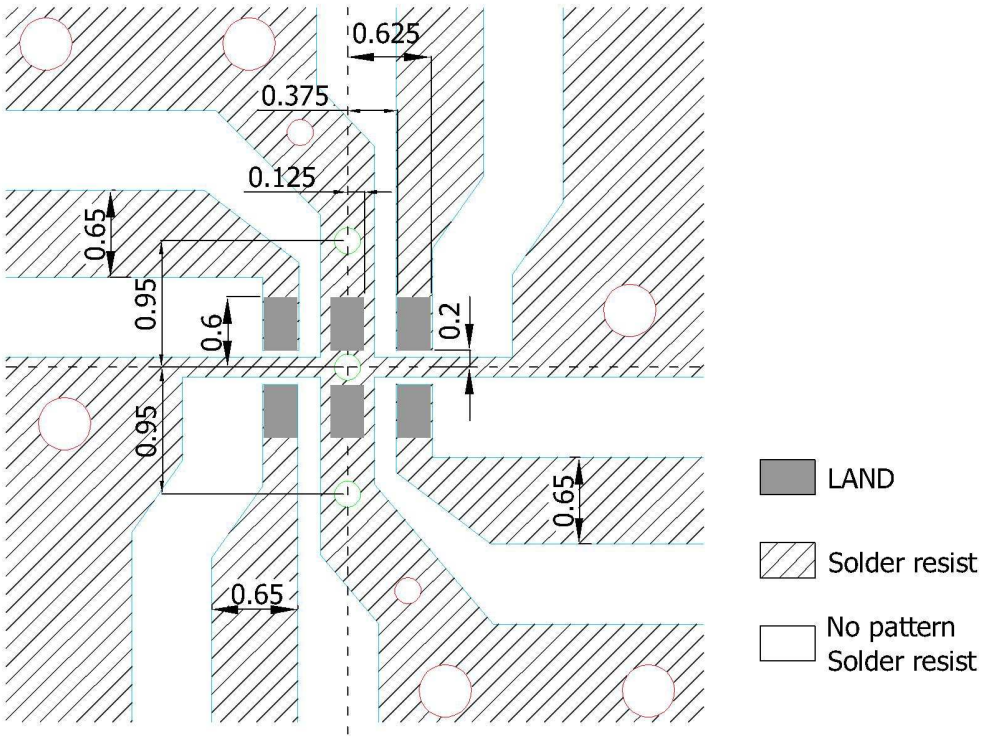
CONSTRUCTION

Figure	PIN	Connection
Top view 	P1	Input
	P2	GND
	P3	Output
	P4	Termination
	P5	GND
	P6	Coupling

DIMENSIONS

Figure	Symbol	Dimension (mm)
	L	1.60 ± 0.10
	W	0.80 ± 0.10
	T	0.70 max.
	A	0.175 ± 0.15
	B	0.25 ± 0.10
	C	0.25 ± 0.10
	D	0.50 ± 0.05
	E	0.20 ± 0.10

SOLDER LAND PATTERN

Figure


Unit : mm

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